

CONSUMER SOLUTIONS



DOWSIL™ TC-5150

Thermally Conductive Gap Filler

How can we reduce heating issues in technological devices?

DOWSIL™ TC-5150 is a one-part non-curable, dispensable thermally conductive gap filler with 5 W/mK thermal conductivity developed to conduct heat from electronics to a heat sink. It will protect your electronic components and enhance your operation's efficiency.

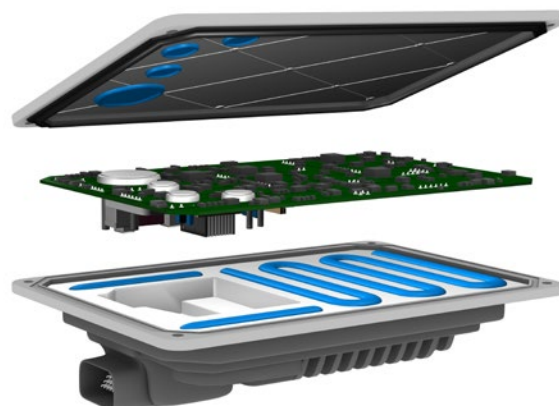


Features and benefits

- High thermal conductivity
- Easily dispensable
- No additional curing process required
- Low thermal impedance
- Reworkable
- Form-in-place
- Requires no mixing or curing
- Can be used with a wide range of designs

Thermal management applications

- Automotive electronic control units
- Processors and microprocessors
- Power electronics
- Telecom base stations
- Power supplies and semiconductors
- Memory and power modules
- Central processing units (CPUs)
- On board chargers



DOWSIL™

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